

# SIDE ENTRY 2-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.

**Contact Resistance:** 20mΩ Max.

**Rating Current:** 1.5A Max.

**Rating Voltage:** 120V AC.

**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.

**Temperature Range:** -40°C / +85°C

**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)

**Soldering Temperature:** 235°C

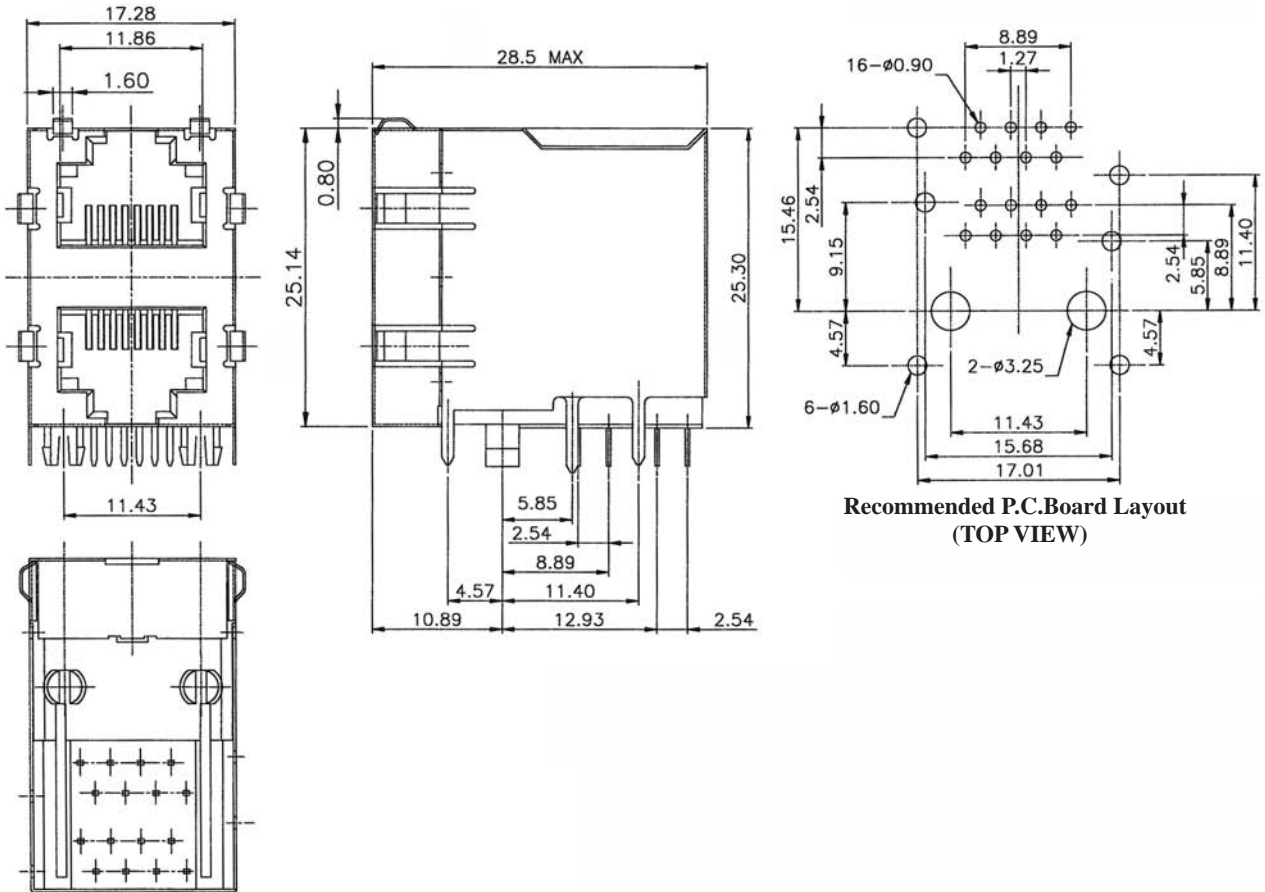
**Color:** Black

**Spring Wire:** Phosphor Bronze

Gold plating Over Nickel

**Shield:** Brass plating Nickel Alloy

**All materials must be RoHS compliant.**



Recommended P.C.Board Layout (TOP VIEW)

## ORDERING INFORMATION:

**P/N M J 4 6 -  $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$**

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: WITH SIDE PANEL GROUNDS

# SIDE ENTRY 4-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.

**Contact Resistance:** 20mΩ Max.

**Rating Current:** 1.5A Max.

**Rating Voltage:** 120V AC.

**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.

**Temperature Range:** -40°C / +85°C

**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)

**Soldering Temperature:** 235°C

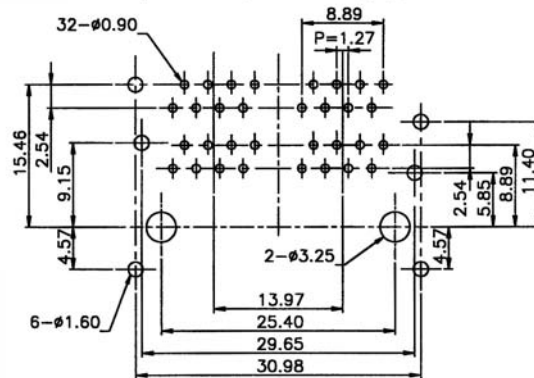
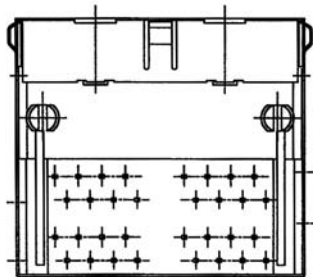
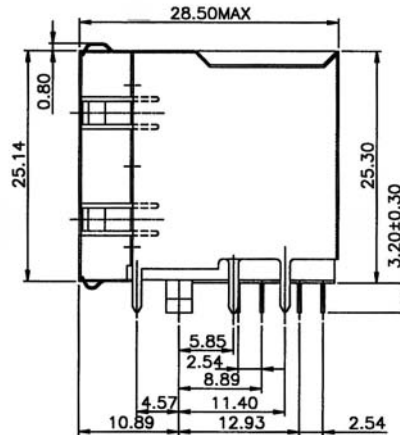
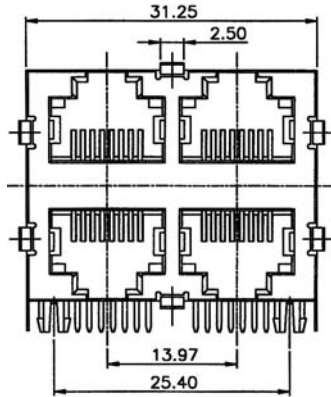
**Color:** Black

**Spring Wire:** Phosphor Bronze

Gold plating Over Nickel

**Shield:** Brass plating Nickel Alloy

All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

P/N M J 4 6 -  $\frac{88}{1}$  x  $\frac{B}{2}$   $\frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: WITH SIDE PANEL GROUNDS

# SIDE ENTRY 6-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.

**Contact Resistance:** 20mΩ Max.

**Rating Current:** 1.5A Max.

**Rating Voltage:** 120V AC.

**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.

**Temperature Range:** -40°C / +85°C

**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)

**Soldering Temperature:** 235°C

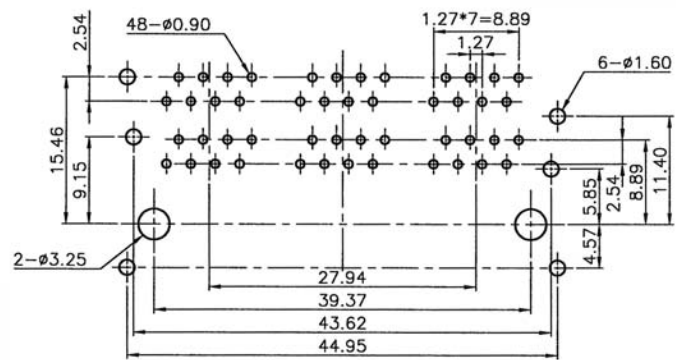
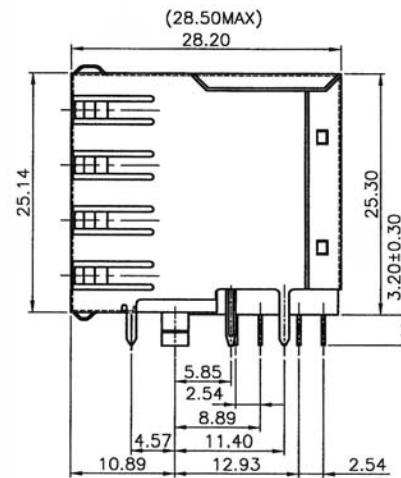
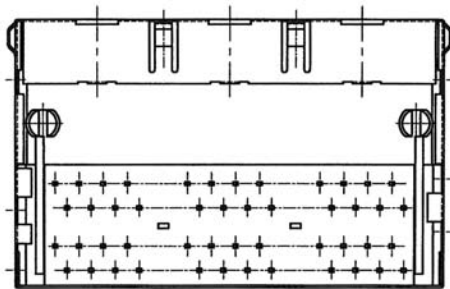
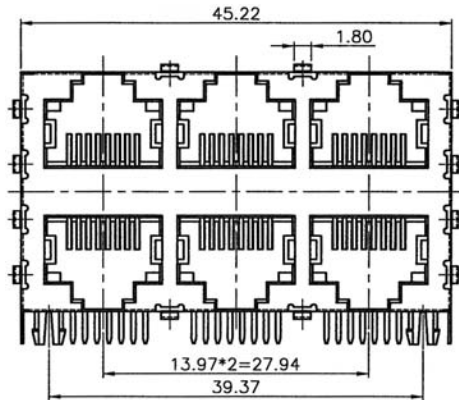
**Color:** Black

**Spring Wire:** Phosphor Bronze

Gold plating Over Nickel

**Shield:** Brass plating Nickel Alloy

All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

P/N M J 4 6 -  $\frac{88}{1} \times \frac{B}{2} \frac{06}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

06

NOTE: WITH SIDE PANEL GROUNDS

# SIDE ENTRY 8-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: Nylon (UL 94V-0)

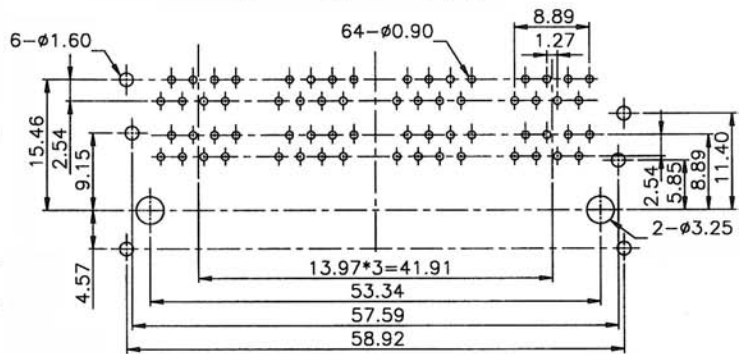
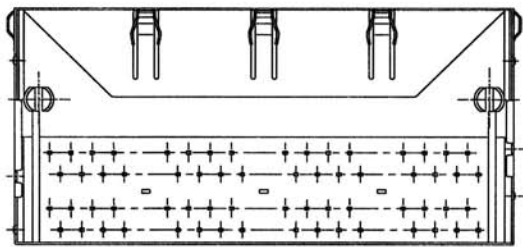
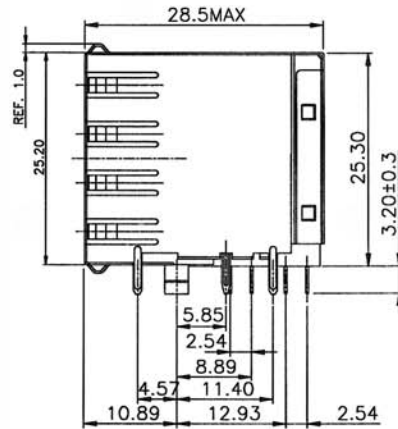
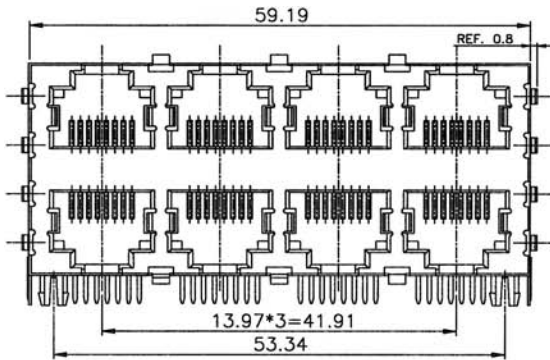
Soldering Temperature: 260°C

Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

P/N M J 4 6 -  $\frac{x}{1} \frac{x}{2} \frac{x}{3} B 0 8$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

08

NOTE: WITH SIDE PANEL GROUNDS

# SIDE ENTRY 2-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.

**Contact Resistance:** 20mΩ Max.

**Rating Current:** 1.5A Max.

**Rating Voltage:** 120V AC.

**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.

**Temperature Range:** -40°C / +85°C

**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)

**Soldering Temperature:** 235°C

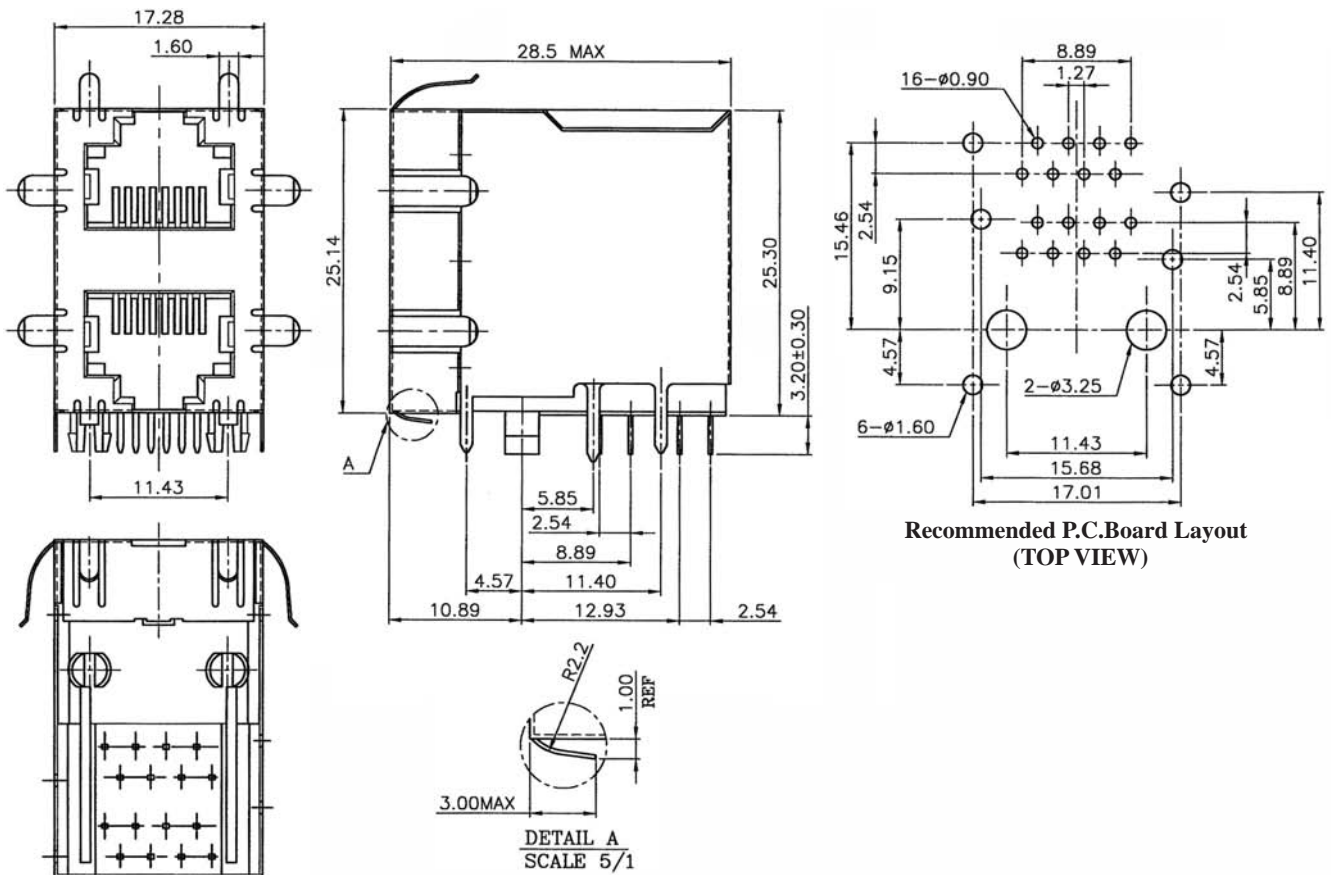
**Color:** Black

**Spring Wire:** Phosphor Bronze

Gold plating Over Nickel

**Shield:** Brass plating Nickel Alloy

All materials must be RoHS compliant.



## ORDERING INFORMATION:

**P/N M J 2 8 -  $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$**

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: WITH TOP & SIDE PANEL GROUNDS

# SIDE ENTRY 4-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.

**Contact Resistance:** 20mΩ Max.

**Rating Current:** 1.5A Max.

**Rating Voltage:** 120V AC.

**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.

**Temperature Range:** -40°C / +85°C

**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)

**Soldering Temperature:** 235°C

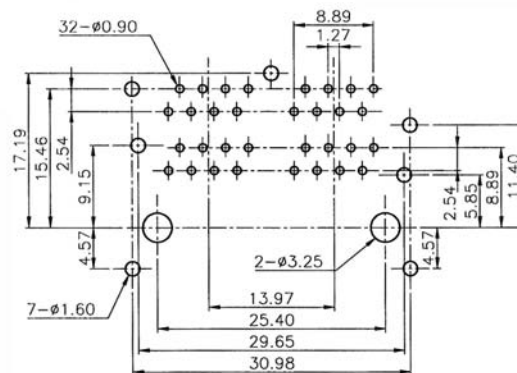
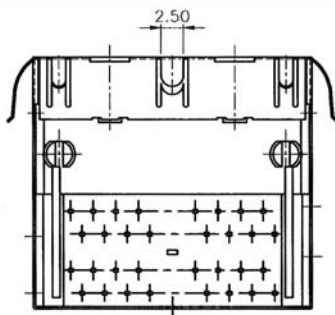
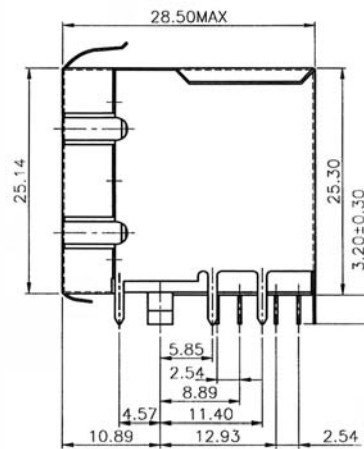
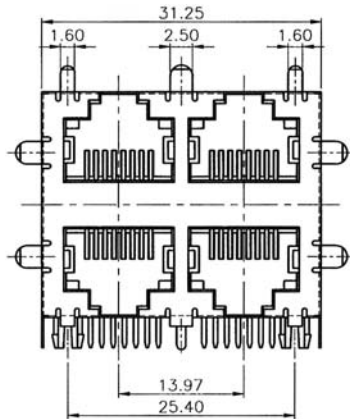
**Color:** Black

**Spring Wire:** Phosphor Bronze

Gold plating Over Nickel

**Shield:** Brass plating Nickel Alloy

**All materials must be RoHS compliant.**



Recommended P.C.Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

**P/N M J 2 8 -  $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$**

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: WITH TOP & SIDE PANEL GROUNDS

# SIDE ENTRY 6-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

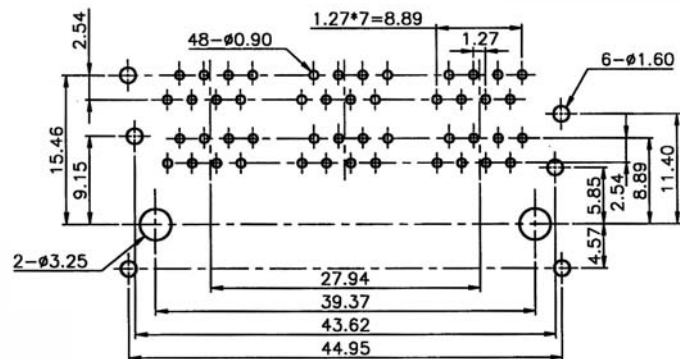
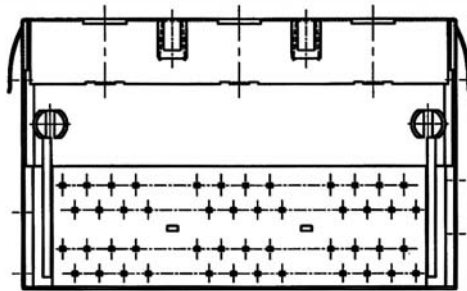
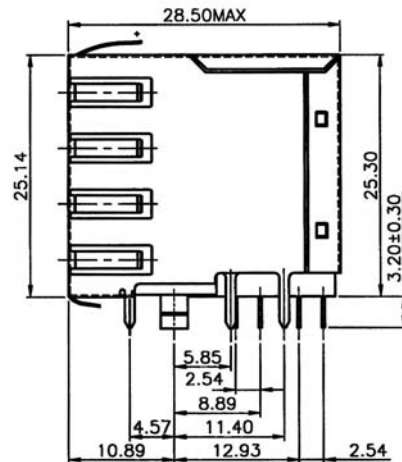
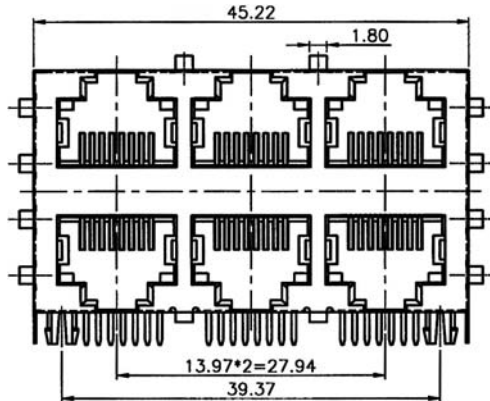
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

P/N M J 2 8 -  $\frac{88}{1} \times \frac{B}{2} \frac{06}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

06

NOTE: WITH TOP & SIDE PANEL GROUNDS

# SIDE ENTRY 8-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.

**Contact Resistance:** 20mΩ Max.

**Rating Current:** 1.5A Max.

**Rating Voltage:** 120V AC.

**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.

**Temperature Range:** -40°C / +85°C

**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)

**Soldering Temperature:** 235°C

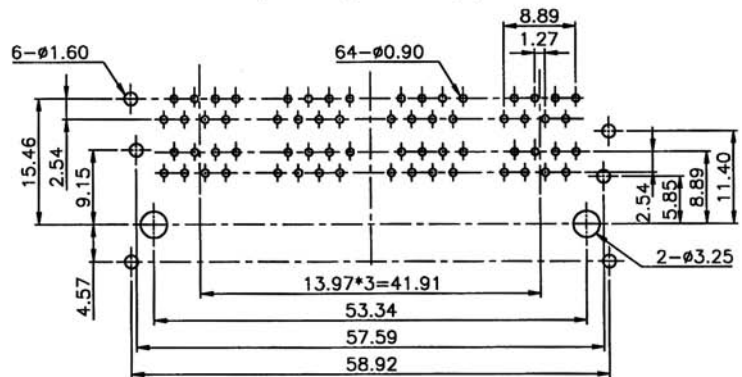
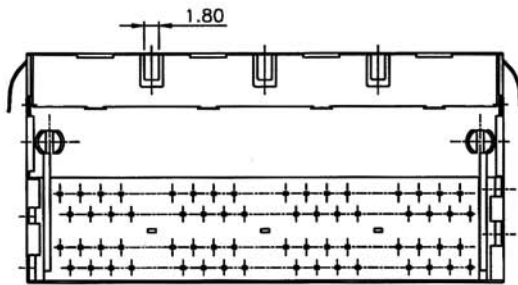
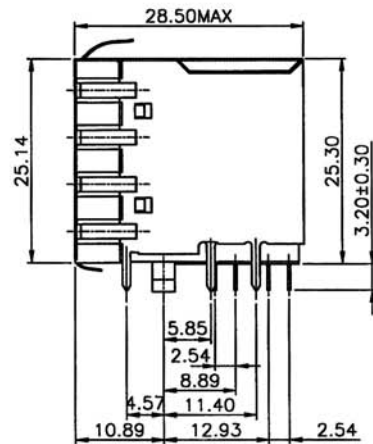
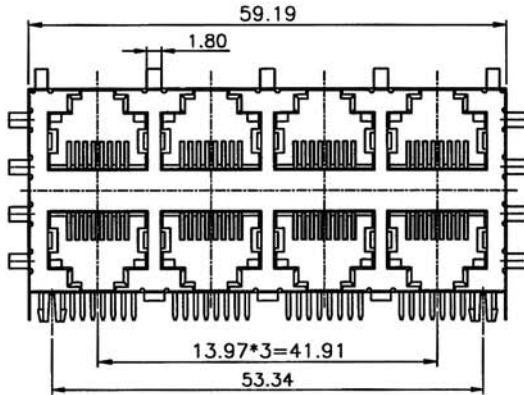
**Color:** Black

**Spring Wire:** Phosphor Bronze

Gold plating Over Nickel

**Shield:** Brass plating Nickel Alloy

All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

P/N M J 2 8 -  $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

08

NOTE: WITH TOP & SIDE PANEL GROUNDS



# SIDE ENTRY 10-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

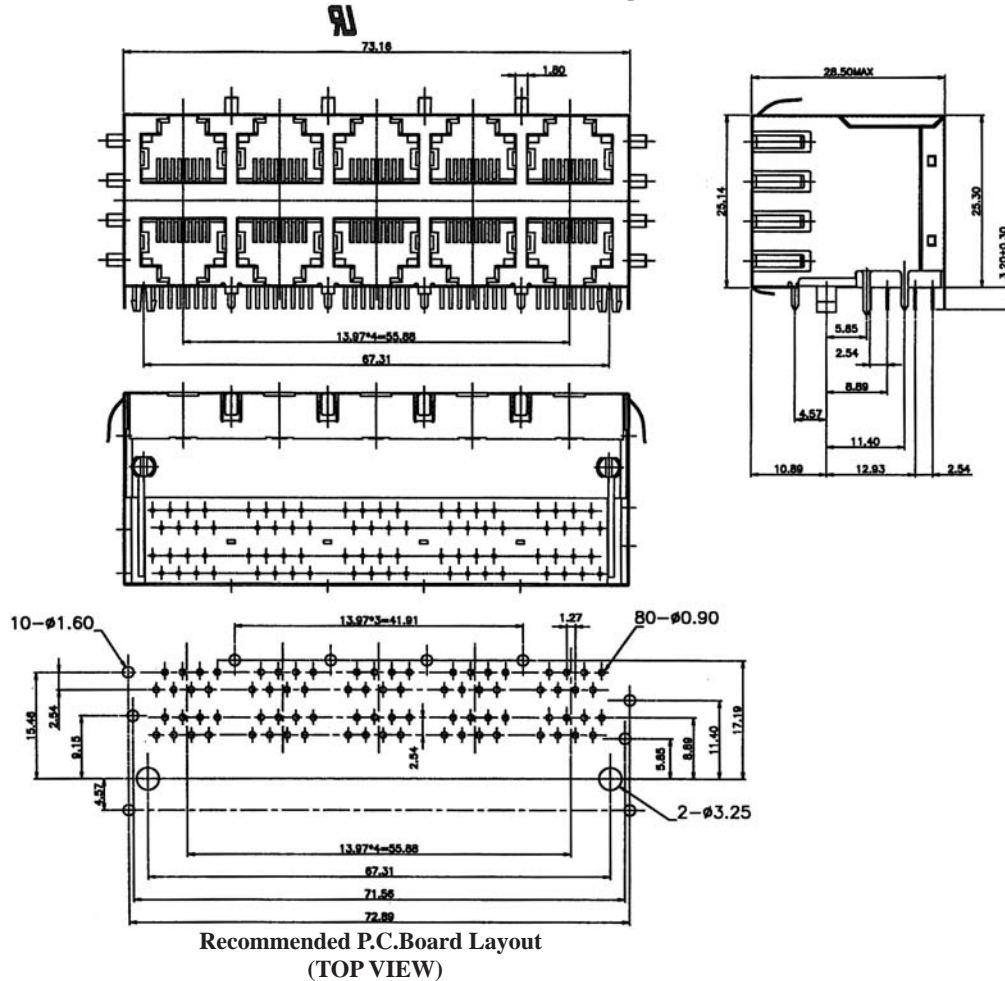
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



## ORDERING INFORMATION:

P/N M J 2 8 -  $\frac{88}{1} \times \frac{B}{2} \frac{10}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

10

NOTE: WITH TOP & SIDE PANEL GROUNDS

# SIDE ENTRY 12-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

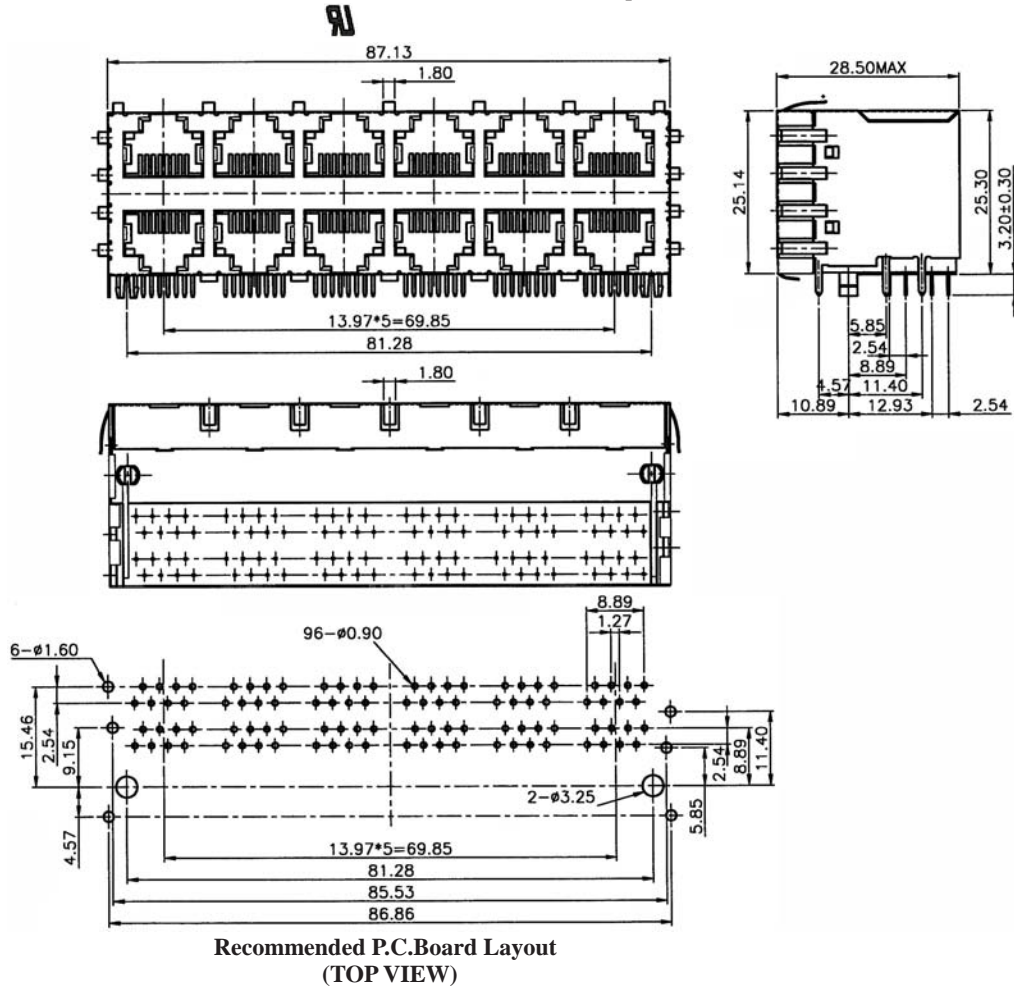
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



## ORDERING INFORMATION:

P/N M J 2 8 -  $\frac{88}{1} \times \frac{B}{2} \frac{12}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

12

NOTE: WITH TOP & SIDE PANEL GROUNDS

# SIDE ENTRY 16-PORT DOUBLE LEVEL MODULAR PCB JACK 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

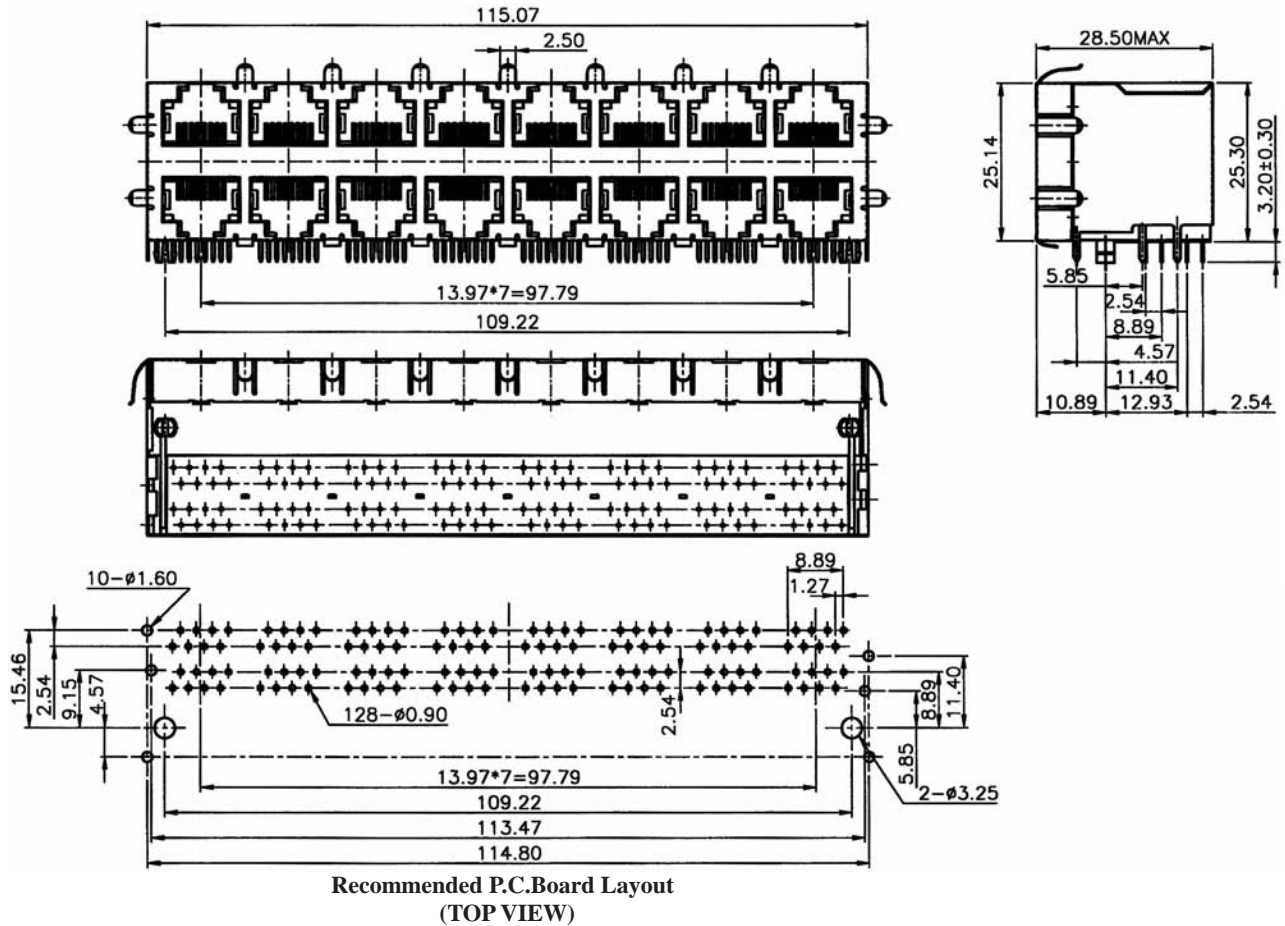
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



## ORDERING INFORMATION:

P/N M J 2 8 -  $\frac{88}{1} \times \frac{B}{2} \frac{16}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

"E" GOLD FLASH

3. NO. OF PORTS:

16

NOTE: WITH TOP & SIDE PANEL GROUNDS

# SIDE ENTRY 2-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

**Insulation Resistance:** 500MΩ Min.

**Contact Resistance:** 20mΩ Max.

**Rating Current:** 1.5A Max.

**Rating Voltage:** 120V AC.

**Dielectric Voltage:** 1000 Vrms 60 Sec. Min.

**Temperature Range:** -40°C / +85°C

**Durability:** 500 Mating cycles Min.

## MATERIALS

**Housing:** PBT Glass Filled (UL 94V-0)

**Soldering Temperature:** 235°C

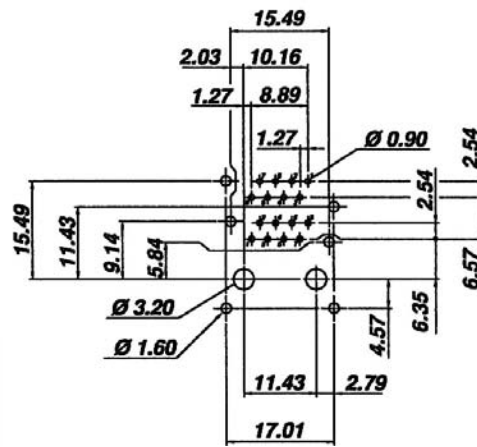
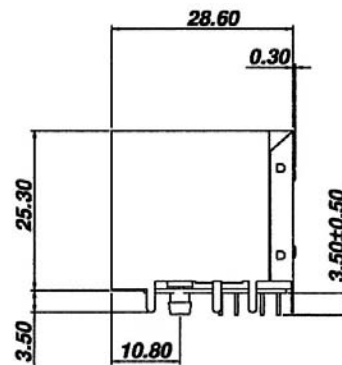
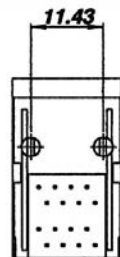
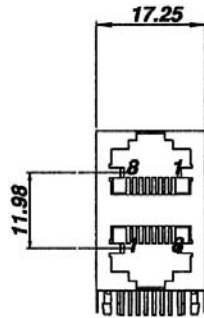
**Color:** Black

**Spring Wire:** Phosphor Bronze

Gold plating Over Nickel

**Shield:** Brass plating Nickel Alloy

All materials must be RoHS compliant.



Recommended P.C.Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

P/N M J D F -  $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: P/N MJDFHT-88xB02 for High Temp. Version

# SIDE ENTRY 4-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

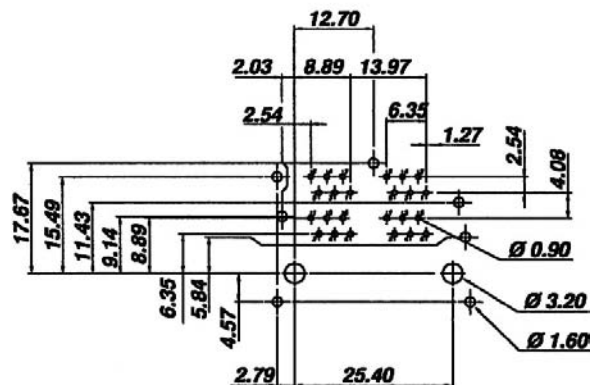
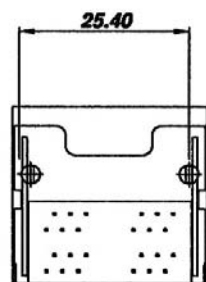
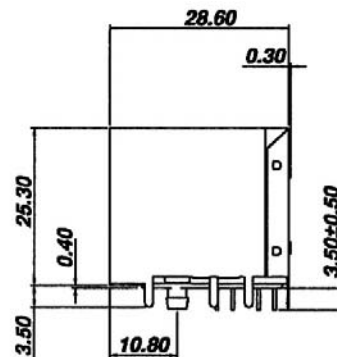
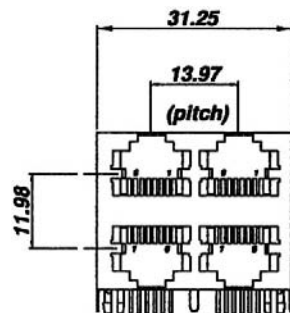
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

P/N M J D F -  $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

04

NOTE: P/N MJDFHT-88xB04 for High Temp. Version

# SIDE ENTRY 8-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

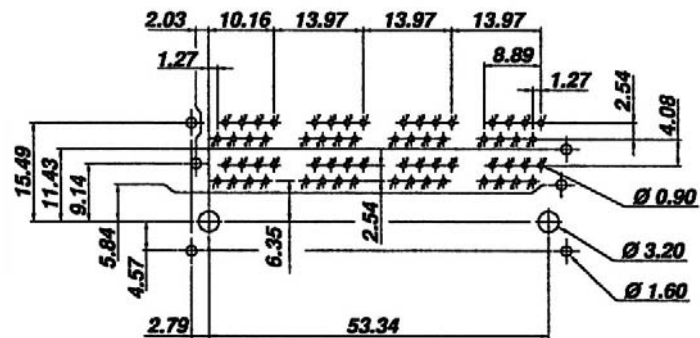
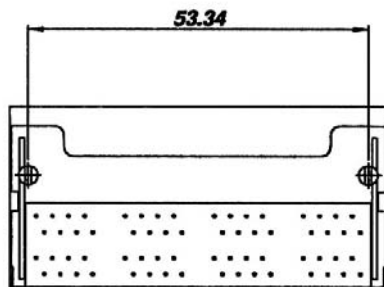
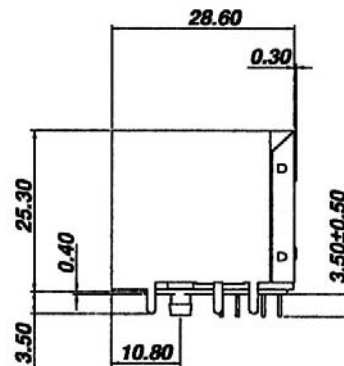
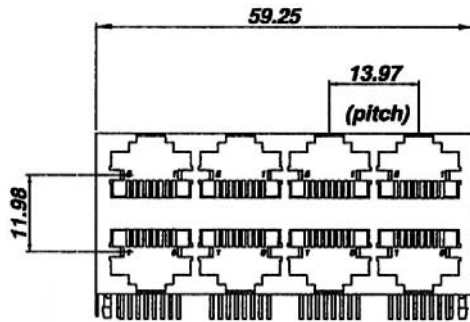
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

P/N M J D F -  $\frac{88}{1} \times \frac{B}{2} \frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

08

NOTE: P/N MJDFHT-88xB08 for High Temp. Version

# SIDE ENTRY 2-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

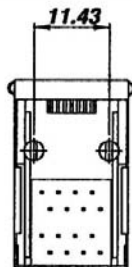
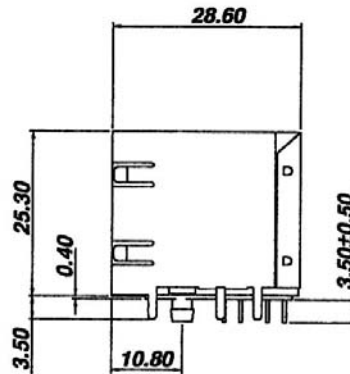
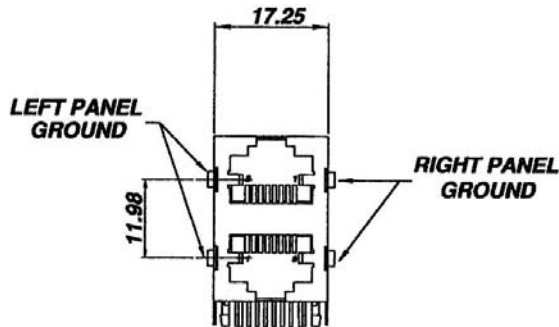
Color: Black

Spring Wire: Phosphor Bronze

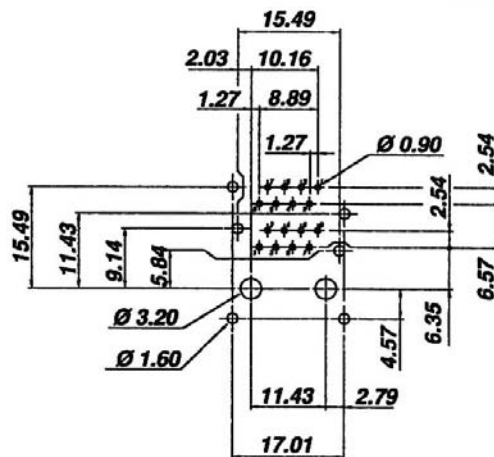
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



**PANEL GROUND MODE**



**Recommended P.C. Board Layout (TOP VIEW)**

## ORDERING INFORMATION:

**P/N MJDE -  $\frac{88}{1} \times \frac{B}{2} \frac{02}{3}$**

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

02

NOTE: P/N MJDEHT-88xB02 for High Temp. Version

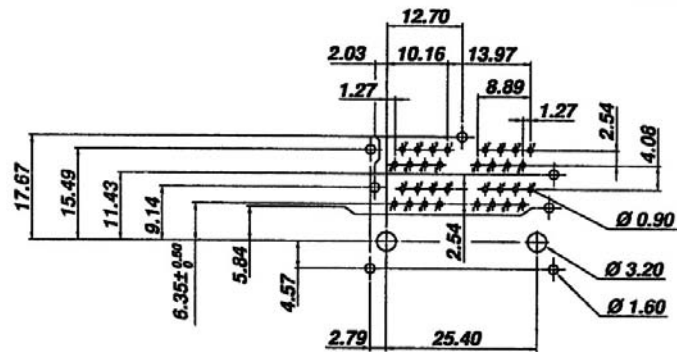
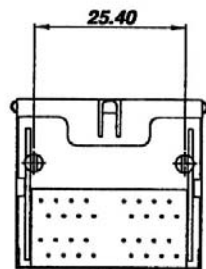
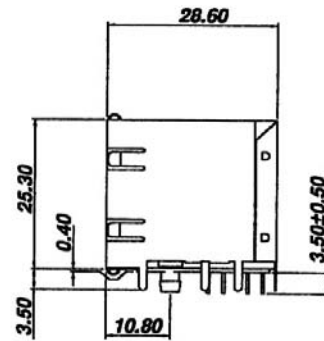
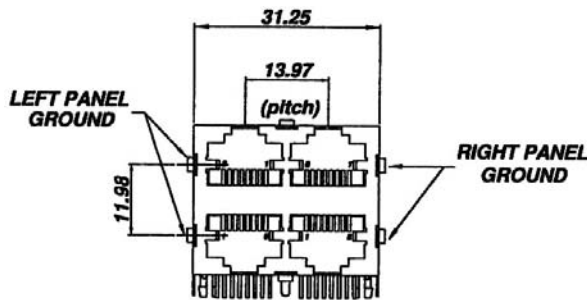
# SIDE ENTRY 4-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.  
 Contact Resistance: 20mΩ Max.  
 Rating Current: 1.5A Max.  
 Rating Voltage: 120V AC.  
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.  
 Temperature Range: -40°C / +85°C  
 Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)  
 Soldering Temperature: 235°C  
 Color: Black  
 Spring Wire: Phosphor Bronze  
 Gold plating Over Nickel  
 Shield: Brass plating Nickel Alloy  
 All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)



PANEL GROUND MODE

## ORDERING INFORMATION:

P/N M J D E -  $\frac{88}{1} \times \frac{B}{2} \frac{04}{3}$

1. NO. OF POSITIONS & CONTACTS:  
"88" 8P8C
2. CONTACT FINISH:  
"A" 6 MICROINCH GOLD  
"B" 15 MICROINCH GOLD  
"C" 30 MICROINCH GOLD  
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:  
04

NOTE: P/N MJDEHT-88xB04 for High Temp. Version



# SIDE ENTRY 6-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

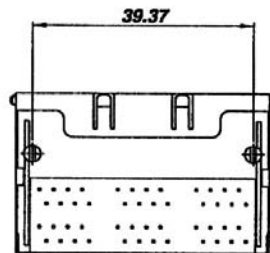
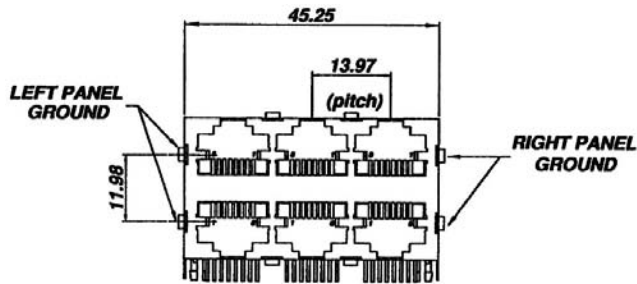
Color: Black

Spring Wire: Phosphor Bronze

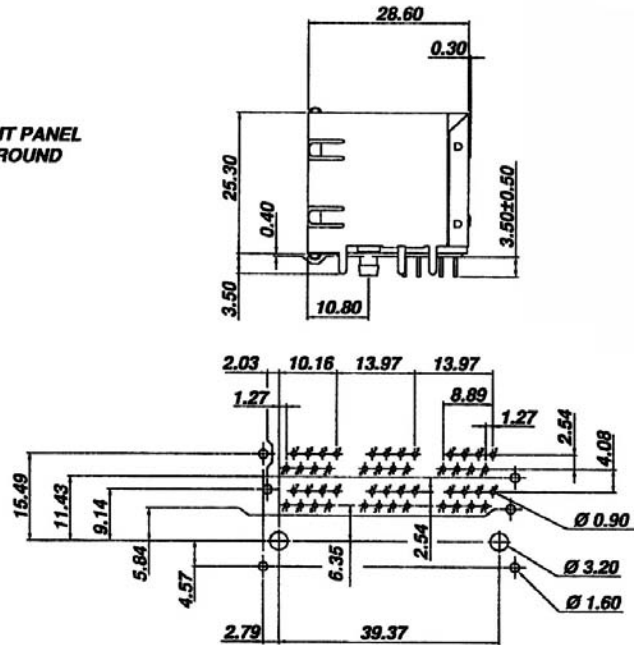
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



**PANEL GROUND MODE**



**Recommended P.C. Board Layout (TOP VIEW)**

## ORDERING INFORMATION:

**P/N MJDE -  $\frac{88}{1} \times \frac{B}{2} \frac{06}{3}$**

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

06

NOTE: P/N MJDEHT-88xB06 for High Temp. Version

# SIDE ENTRY 8-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

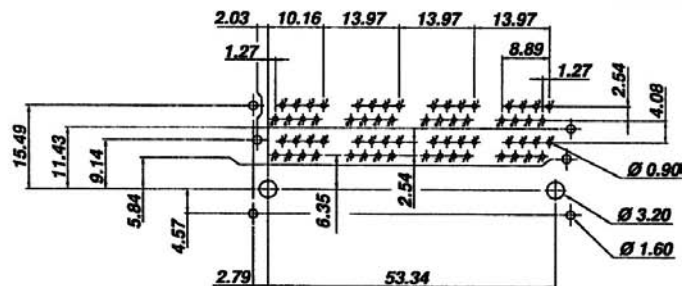
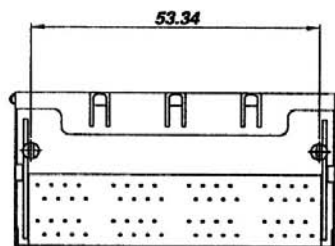
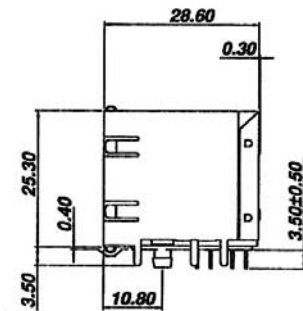
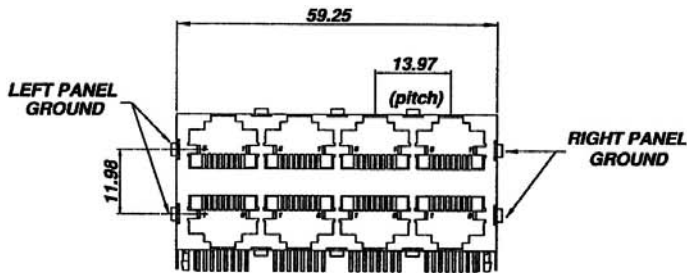
Color: Black

Spring Wire: Phosphor Bronze

Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



Recommended P.C. Board Layout  
(TOP VIEW)



PANEL GROUND MODE

## ORDERING INFORMATION:

P/N M J D E -  $\frac{88}{1}$  x  $\frac{B}{2}$   $\frac{08}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

08

NOTE: P/N MJDEHT-88xB08 for High Temp. Version

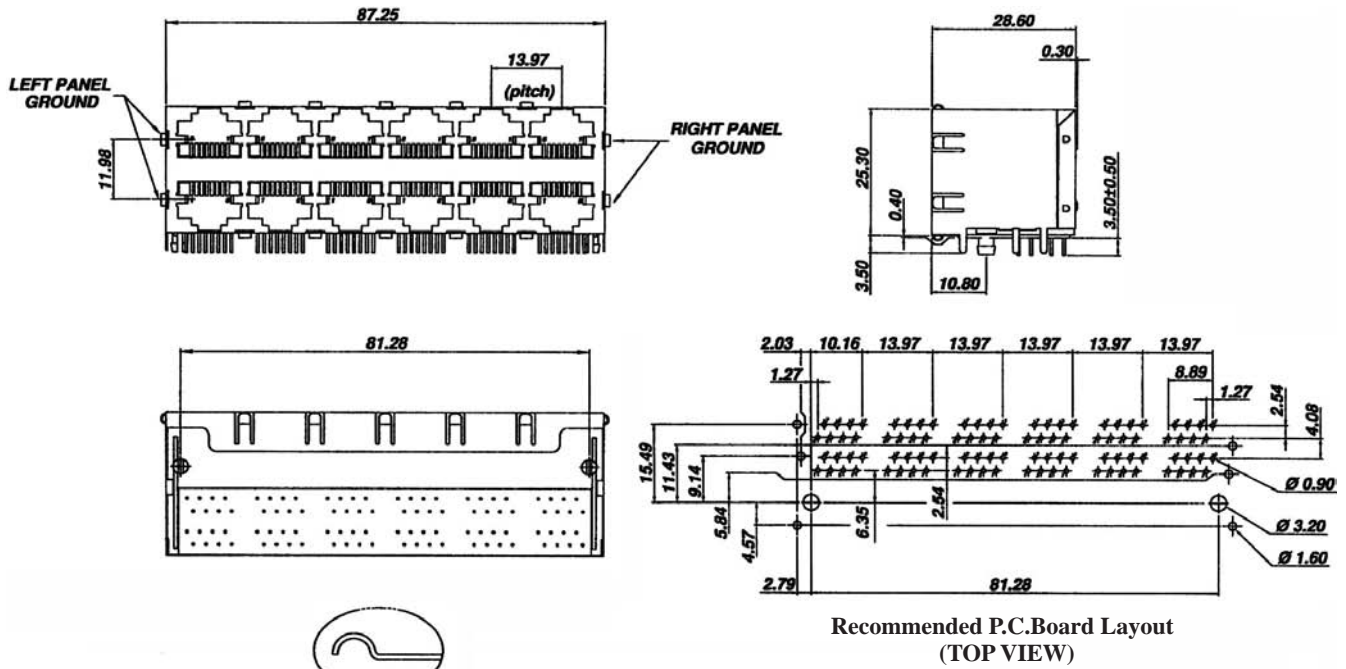
# SIDE ENTRY 12-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.  
 Contact Resistance: 20mΩ Max.  
 Rating Current: 1.5A Max.  
 Rating Voltage: 120V AC.  
 Dielectric Voltage: 1000 Vrms 60 Sec. Min.  
 Temperature Range: -40°C / +85°C  
 Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)  
 Soldering Temperature: 235°C  
 Color: Black  
 Spring Wire: Phosphor Bronze  
 Gold plating Over Nickel  
 Shield: Brass plating Nickel Alloy  
 All materials must be RoHS compliant.



PANEL GROUND MODE

## ORDERING INFORMATION:

P/N MJDE -  $\frac{88}{1} \times \frac{B}{2} \frac{12}{3}$

1. NO. OF POSITIONS & CONTACTS:  
"88" 8P8C
2. CONTACT FINISH:  
"A" 6 MICROINCH GOLD  
"B" 15 MICROINCH GOLD  
"C" 30 MICROINCH GOLD  
"D" 50 MICROINCH GOLD
3. NO. OF PORTS:  
12

NOTE: P/N MJDEHT-88xB12 for High Temp. Version

# SIDE ENTRY 16-PORT DOUBLE LEVEL MODULAR PCB JACK WITH INNER SHIELD 8P PROFILE=25.30MM (FULLY SHIELDED)

## SPECIFICATIONS

Insulation Resistance: 500MΩ Min.

Contact Resistance: 20mΩ Max.

Rating Current: 1.5A Max.

Rating Voltage: 120V AC.

Dielectric Voltage: 1000 Vrms 60 Sec. Min.

Temperature Range: -40°C / +85°C

Durability: 500 Mating cycles Min.

## MATERIALS

Housing: PBT Glass Filled (UL 94V-0)

Soldering Temperature: 235°C

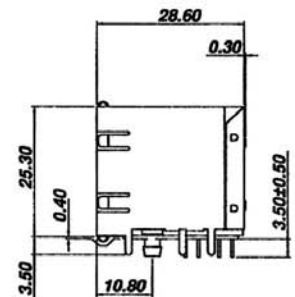
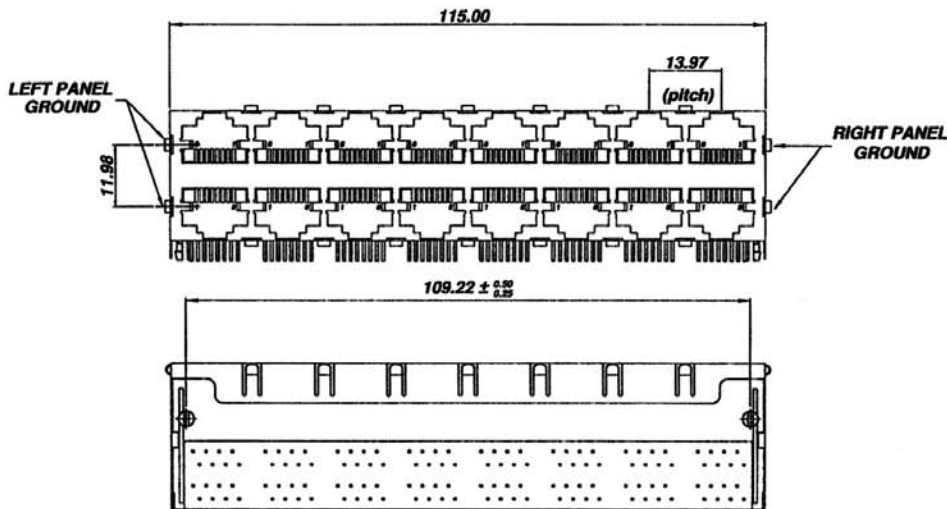
Color: Black

Spring Wire: Phosphor Bronze

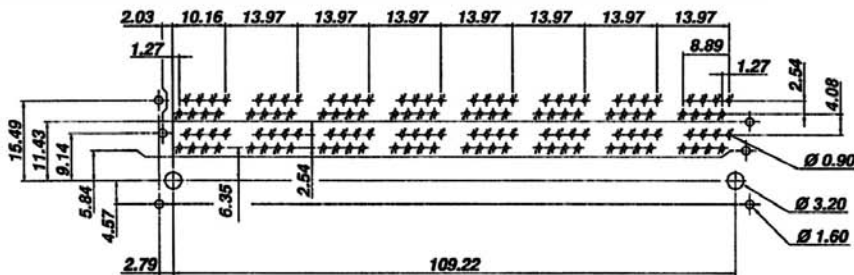
Gold plating Over Nickel

Shield: Brass plating Nickel Alloy

All materials must be RoHS compliant.



**PANEL GROUND MODE**



Recommended P.C. Board Layout  
(TOP VIEW)

## ORDERING INFORMATION:

P/N M J D E -  $\frac{88}{1} \times \frac{B}{2} \frac{16}{3}$

1. NO. OF POSITIONS & CONTACTS:

"88" 8P8C

2. CONTACT FINISH:

"A" 6 MICROINCH GOLD

"B" 15 MICROINCH GOLD

"C" 30 MICROINCH GOLD

"D" 50 MICROINCH GOLD

3. NO. OF PORTS:

16

NOTE: P/N MJDEHT-88xB16 for High Temp. Version